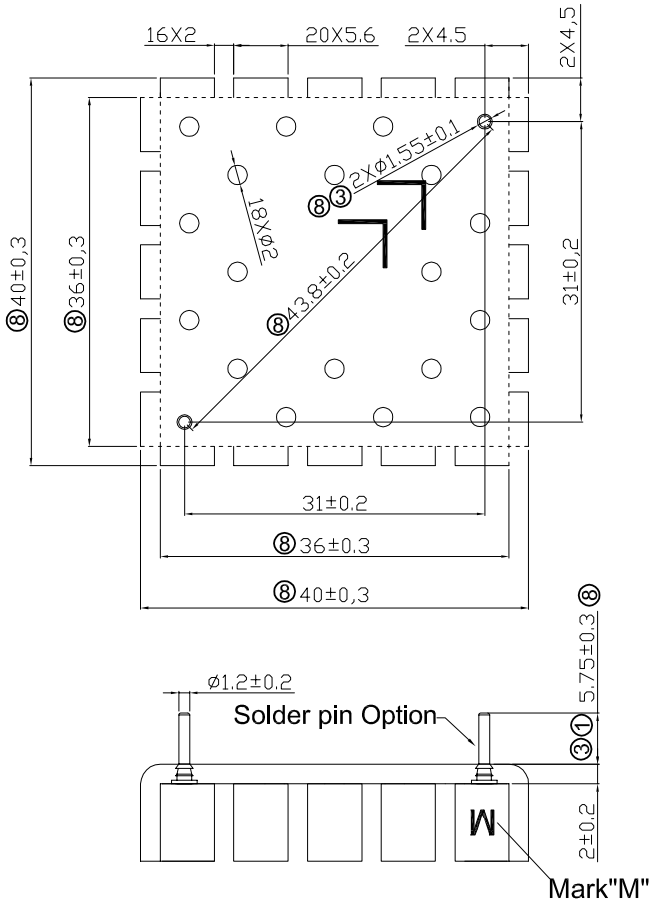
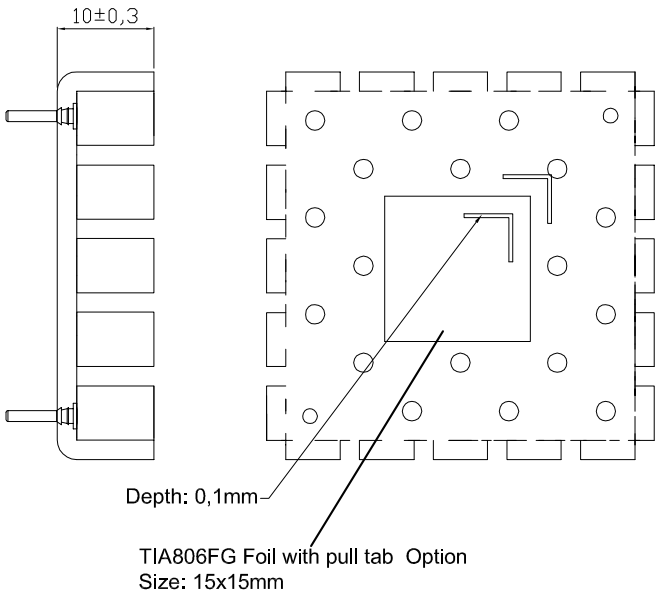
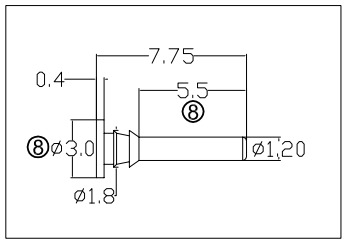




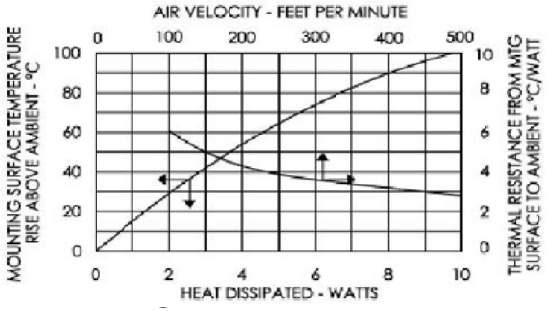


③ Detail Pin
2 : 1

Notes:
Material: AL 1050
Finish: Nature anodized
Pin material: Fe
Plating: Tin
④ Recommended IC size: ≤ 30x30mm
Recommended IC power: ≤ 5W

④ WSW order code:

V2136N:	w/o foil, w/o solder pin
V2136N1:	w/o foil , with solder pin
V2136N1-F:	with foil , w/o solder pin
V2136N1-F-LP:	with foil & with solder pin



RoHS compliant
Unit: mm

Scale	Free	
⑧ TOLERANCE		
Less 10	±0.10	
10~30	±0.20	
31~50	±0.30	
51~100	±0.50	
DIM	Tol	
Angle	±1°	

Id.	Modification	Date	Name
⑧	Update tolerance	29.05.2018	Segal
⑦	Add IC size and power in notes	22.05.2018	Amy
⑥	Change the foil on page 2/3	23.06.2016	Amy
⑤	Add thermal resistance graph	19.02.2016	Amy
④	Add new version	25.01.2016	Amy
③	Update the solder pin	21.05.2015	Amy

	Date	Name
Drawn	02.05.2013	Amy
Approved	29.05.2018	Amy

ASSMANN WSW components

Customer-No.

ASSMANN WSW-No. V2136Nx-x

Drawing-No. ASS 2103 HS

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TIA 806FG product is mostly used for bonding heat dissipation fins,microprocessors and other power consumption semiconductors. This type of adhesive tape possesses ultimate bonding strength with low thermal impedance, with which in effect can be able to replace the method of lubricating grease and mechanical fixing.

Feature
Thermal Conductivity 1.0W/mK
High bond strength to a variety of surfaces
Double sided pressure sensitive adhesive tape
High performance, thermally conductive acrylic adhesive

Application
Mount heat sink onto BAG graphic processor or drive processor
Mount heat spreader onto power converter PCB or onto motor control PCB
High performance, thermally conductive acrylic adhesive
Can be used instead of heat cure adhesive, screw mounting or clip mounting

Typical Properties	TIA™806FG			Test Method
Color	White			Visual
Adhesive Type	Acrylic Adhesive			********
Backing Type	Fiberglass			********
Continuous Use Temp	-45 °C to 120 °C			********
ThicknessThickness	0.006" 0.152mm			ASTM D374
Thickness Tolerance	±0.001" ±0.025mm			ASTM D374
Voltage Breakdown	> 3000 Vac			ASTM D149
Tensile Strength	120psi			ASTM D412
Thermal Impedance @50psi	0.59℃-in²/W			ASTM D5470
Thermal Conductivity	1.0 W/mK			ASTM D5470
Peel Adhesion	> 1000 g/inch (Steel, Immediate)			PSTC-1
Peel Adhesion	> 1200 g/inch (Steel after 24 hrs)			PSTC-1
Holding Power (25 °C/Hours)	> 48 Hours			PSTC-7
Holding Power (80 °C/Hours)	> 48 Hours			PSTC-7
Recommend Using Pressure	Pressure	Temperature	Time	********
	10 psi (0.069 MPa)	25°C	20 sec	
	10 psi (0.069 MPa)	50 °C - 65 °C	5 sec	
Shelf Life	1 year when stored at room temperature			********

RoHS compliant
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ASSMANN WSW components

Customer-No.

ASSMANN WSW-No. V2136Nx-x

Drawing-No. ASS 2103 HS

rev08

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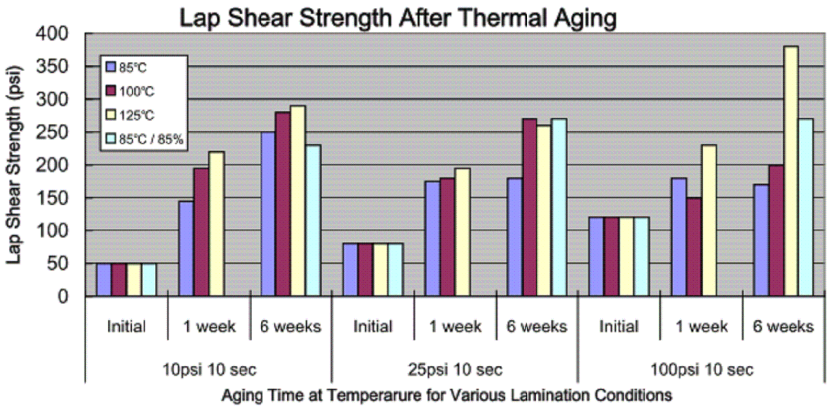
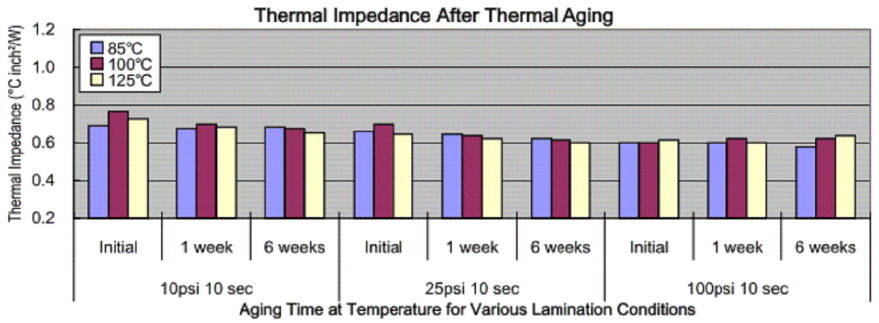
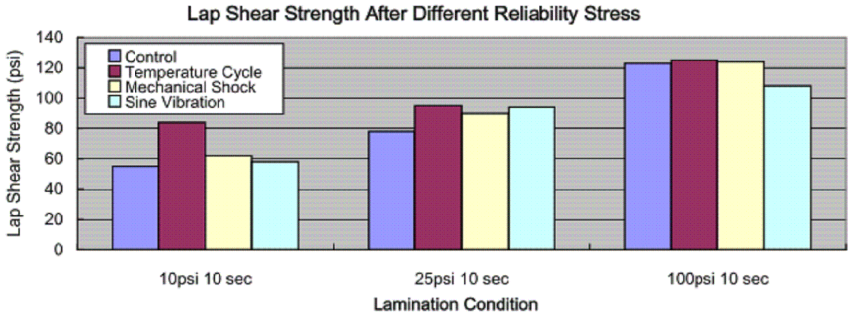
Thermal Cycling Reliability Test
TIA806FG

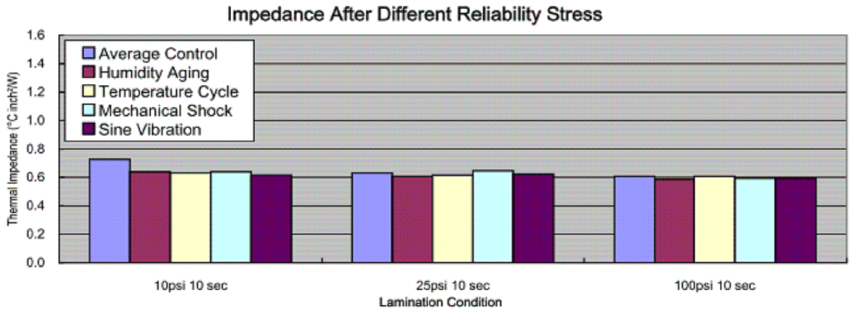
The long term reliability of TIA806FG tape was evaluated. Lap shear strength and thermal impedance were measured after exposing to various aging environments. Lap shear samples were prepared by sandwiching TIA806FG tape between Al substrates with 1x1 inch² overlap. Thermal samples for reliability testing were also prepared by laminating the tape between Al substrates at various pressures. TIA806FG exhibits excellent stability and passes thermal and adhesion properties after various aging conditions.

- **Thermal aging: 1000 hours at three different temperatures: 85°C, 100°C and 125°C**
- **Thermal/ humidity aging: 1000 hours at 85°C/85% relative humidity**
- **Thermal shock: temperature ramp from -40 to 125°C at a rate of 10°C/minute with 10 minute hold at peaks for 100 cycles**
- **Mechanical shock: 3 blows in 6 directions (total of 18) with 60G's force in half sine pulse**
- **Sine vibration: vibration between 10 to 2000Hz with 2grams to 12grams force on X and Y axis only**









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Unit: mm

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ASSMANN WSW components

Customer-No.

ASSMANN WSW-No. V2136Nx-x

Drawing-No. ASS 2103 HS

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